

**Table S3. Electrical Characteristics for Surface-mount Devices *continued***

Part Number	$I_H$ (A)	$I_T$ (A)	$V_{MAX}$ (V <sub>DC</sub> )	$I_{MAX}$ (A)	$P_D$ TYP (W)	Max. Time-to-Trip		$R_{MIN}$ ( $\Omega$ )	$R_{TYP}$ ( $\Omega$ )	$R_{1MAX}$ ( $\Omega$ )	Figures for Dimensions
						(A)	(s)				
<b>miniSMD <i>continued</i></b>											
<b>Size 4532 mm/1812 mils</b>											
miniSMDM200F <sup>†</sup>	† 2.00	3.50	8	40	0.6	8.0	3.00	0.020	0.040	0.060	S5
miniSMDC260	2.60	5.00	6	40	0.6	8.0	7.00	0.015	0.035	0.047	S3
miniSMDM260	† 2.60	4.55	6	40	0.6	8.0	6.00	0.010	0.030	0.043	S5
miniSMDM260F <sup>†</sup>	† 2.60	4.55	6	40	0.6	8.0	6.00	0.010	0.030	0.043	S5
<b>miniSMDE</b>											
<b>Size 11550 mm/4420 mils</b>											
miniSMDE190	1.90	3.80	16	100	1.4	10	2.0	0.024	0.065	0.080	S3
<b>midSMD</b>											
<b>Size 5050 mm/2018 mils</b>											
SMD030-2018	0.30	0.80	60	20	0.7	1.5	1.5	0.500	1.40	2.300	S6
SMD050-2018	0.55	1.20	57	10	1.0	2.5	5.0	0.200	—	1.000	S6
SMD100-2018	1.10	2.20	15	40	1.2	8.0	0.5	0.100	0.25	0.400	S6
SMD150-2018	1.50	3.00	15	40	1.4	8.0	1.0	0.070	0.13	0.180	S6
SMD200-2018	2.00	4.20	6	40	1.4	8.0	3.0	0.048	0.07	0.100	S6
<b>SMD</b>											
<b>Size 7555 mm/2920 mils</b>											
SMD030	0.30	0.60	60	10	1.5	1.5	3.0	1.200	3.00	4.800	S7
SMD050	0.50	1.00	60	10	1.5	2.5	4.0	0.350	0.87	1.400	S7
SMD075	0.75	1.50	30	40	1.5	8.0	0.3	0.350	0.67	1.000	S7
SMD075F <sup>†</sup>	0.75	1.50	30	40	1.5	8.0	0.3	0.350	0.67	1.000	S7
SMD100	1.10	2.20	30	40	1.5	8.0	0.5	0.120	0.30	0.480	S7
SMD100/33	1.10	2.20	33	40	1.5	8.0	0.5	0.120	0.27	0.410	S7
SMD125	1.25	2.50	15	40	1.5	8.0	2.0	0.070	0.16	0.250	S7
SMD260	2.60	5.20	6	40	1.5	8.0	20.0	0.025	0.05	0.075	S7
SMD260-RB	2.60	5.00	6	40	1.5	5.0	60.0	0.030	0.055	0.075	S7
SMD300	3.00	6.00	6	40	1.3	8.0	35.0	0.015	0.033	0.048	S7
<b>SMD2</b>											
<b>Size 8763 mm/3425 mils</b>											
SMD150	1.50	3.00	15	40	1.7	8.0	5.0	0.060	0.16	0.250	S7
SMD150/33	1.50	3.00	33	40	1.7	8.0	5.0	0.080	0.15	0.230	S7
SMDH160	1.60	3.20	16	70	2.1	8.0	15.0	0.050	0.10	0.150	S7
SMD185	1.80	3.60	33	40	1.2	8.0	5.0	0.065	0.12	0.165****	S7
SMD200	2.00	4.00	15	40	1.7	8.0	12.0	0.050	0.09	0.125	S7
SMD250	2.50	5.00	15	40	1.7	8.0	25.0	0.035	0.06	0.085	S7
<b>Telecom Surface-mount**</b>											
TSL250-080	0.08	0.16	250***	3.0	1.2	1.0	1.8	5.0	11.0	20.0****	S7
TS250-130	0.13	0.26	250*** 650	3.0 1.1	1.1	1.0	2.5	6.5	12.0	20.0	S8
TSV250-130	0.13	0.26	250***	3.0	1.5	1.0	3.0	4.0	7.0	12.0****	S10
TS600-170	0.17	0.40	600***	3.0	2.5	1.0	21.0	4.0	9.0	18.0	S9
TS600-200-RA	0.20	0.40	600***	3.0	2.5	1.0	21.0	4.0	7.5	13.5	S9
TSM600-250	0.25	0.86	600***	3.0	2.0	3.0	6.0	1.0	3.5	7.0	—
TSM600-250-RA	0.25	0.86	600***	3.0	2.0	3.0	6.0	1.0	3.0	5.0	—

\*F: lead-free device †Electrical characteristics determined at 25°C.

\*\*These products are intended for telecom applications. Time-to-trip is typical, please see Telecom and Networking section for details.

\*\*\*RMS max. voltage.

\*\*\*\* $R_{1MAX}$  is measured one hour post-trip or 24 hours post-reflow at 20°C.

$I_H$  = Hold current: maximum current device will pass without interruption in 20°C still air.

$I_T$  = Trip current: minimum current that will switch the device from low resistance to high resistance in 20°C still air.

$V_{MAX}$  = Maximum voltage device can withstand without damage at rated current.

$I_{MAX}$  = Maximum fault current device can withstand without damage at rated voltage.

$P_D$  = Power dissipated from device when in the tripped state in 20°C still air.

$R_{1MAX}$  is measured one hour post reflow.

$R_{TYP}$  = Typical resistance of device as supplied at 20°C unless otherwise specified.